

Title (en)

CERAMIC ELECTRONIC MULTILAYER COMPONENT AND METHOD FOR THE PRODUCTION THEREOF

Title (de)

KERAMISCHES ELEKTRONISCHES MEHRSCHICHTBAUELEMENT UND VERFAHREN ZU DESSEN HERSTELLUNG

Title (fr)

COMPOSANT ÉLECTRONIQUE CÉRAMIQUE À COUCHES MULTIPLES ET SON PROCÉDÉ DE FABRICATION

Publication

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Application

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Abstract (en)

[origin: WO2010092027A1] The invention relates to a multilayer component that comprises a dielectric ceramic material that can be co-sintered with a varistor ceramic to form a monolithic multilayer component according to the invention. Therefore, the multilayer component comprises a layer of a varistor ceramic and another layer of a dielectric. The two layers can be arranged directly adjacent in the multilayer component. In the multilayer component, metallizations that are structured to form conductor sections and metallized surfaces are arranged on or between the ceramic layers. In addition to a varistor, the metallizations, together with the ceramic layers, also form at least one further component that is selected from at least one of the component functions of capacitance, resistance, and inductance.

IPC 8 full level

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